

METHOD FOR MOLDING A SEMICONDUCTOR DEVICE

Abstract of the Disclosure

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A mold tool (40) includes a lower platen (10) and an upper platen (18) which have modified surfaces (16) and (20), respectively. The modified surfaces are formed by implanting an implant species (14) at least into areas of the platens which will be in contact with a molding compound resin. By
10 modifying the surface of the molding tool by ion implantation, the need for cleaning the mold tool is reduced due to lower surface friction and wettability of the modified surfaces. These surface characteristics also facilitate easier release of the molded package from the tool. At the same
15 time, wear resistance of the mold tool is improved due to increased surface hardness.

Figure 4 accompanies this abstract.